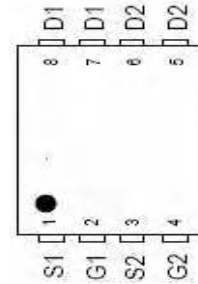
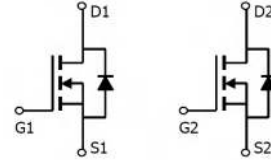


Dual N-Channel Shielding-Gate Mosfet

Feature

- 60V,40A
 $R_{DS(ON)} < 14.5m\Omega @ V_{GS}=10V$ (TYP:11.5m Ω)
 $R_{DS(ON)} < 17.5m\Omega @ V_{GS}=4.5V$ (TYP:14.5m Ω)
- Split Gate Trench Technology
- Lead free product is acquired
- Excellent $R_{DS(ON)}$ and Low Gate Charge
- $T_{jmax}=175^{\circ}C$



pin assignment

Application

- PWM applications
- Load Switch
- Power management
- P/N suffix V means AEC-Q101 qualified, e.g:RMD40N60DFV
- Halogen-free

Package Marking and Ordering Information

Device Marking	Device	Package	Packaging Code	Reel Size	Quantity(Pcs)	Carton(Pcs)
D40N60	RMD40N60DFV	DFN5X6	-W	13inch	5000	80000

ABSOLUTE MAXIMUM RATINGS ($T_J=25^{\circ}C$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	60	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current ($T_c=25^{\circ}C$)	I_D	40	A
Continuous Drain Current ($T_c=100^{\circ}C$)	I_D	27	A
Pulsed Drain Current ⁽¹⁾	I_{DM}	180	A
Single Pulsed Avalanche Energy ⁽²⁾	E_{AS}	36	mJ
Power Dissipation	P_D	60	W
Thermal Resistance from Junction to Case	$R_{\theta JC}$	2.5	$^{\circ}C/W$
Thermal Resistance from Junction to Ambient	$R_{\theta JA}$	62.5	$^{\circ}C/W$
Junction Temperature	T_J	175	$^{\circ}C$
Storage Temperature	T_{STG}	-55~ +175	$^{\circ}C$

MOSFET ELECTRICAL CHARACTERISTICS($T_J=25^{\circ}\text{C}$ unless otherwise noted)

Parameter	Symbol	Test Condition	Min	Type	Max	Unit
Static Characteristics						
Drain-source breakdown voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	60	-	-	V
Zero gate voltage drain current	I_{DSS}	$V_{DS} = 60V, V_{GS} = 0V$	-	-	1	μA
Gate-body leakage current	I_{GSS}	$V_{GS} = \pm 20V, V_{DS} = 0V$	-	-	± 100	nA
Gate threshold voltage ⁽³⁾	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu A$	1.2	1.6	2.2	V
Drain-source on-resistance ⁽³⁾	$R_{DS(on)}$	$V_{GS} = 10V, I_D = 20A$	-	11.5	14.5	m Ω
		$V_{GS} = 4.5V, I_D = 10A$	-	14.5	17.5	m Ω
Forward Threshold Voltage	g_{fs}	$V_{DS} = 5V, I_D = 20A$	-	60	-	S
Dynamic characteristics						
Input Capacitance	C_{iss}	$V_{DS} = 25V, V_{GS} = 0V, f = 1MHz$	-	1000	-	pF
Output Capacitance	C_{oss}		-	220	-	
Reverse Transfer Capacitance	C_{rss}		-	9	-	
Switching characteristics						
Turn-on delay time	$t_{d(on)}$	$V_{DD} = 30V, I_D = 20A,$ $V_{GS} = 10V, R_G = 1.6\Omega$	-	4.5	-	ns
Turn-on rise time	t_r		-	2.7	-	
Turn-off delay time	$t_{d(off)}$		-	13.5	-	
Turn-off fall time	t_f		-	2.7	-	
Total Gate Charge	Q_g	$V_{DS} = 30V, I_D = 20A,$ $V_{GS} = 10V$	-	22	-	nC
Gate-Source Charge	Q_{gs}		-	4.6	-	
Gate-Drain Charge	Q_{gd}		-	3.5	-	
Reverse Recovery Charge	Q_{rr}	$I_F = 20A, di/dt = 100A/\mu s$		12		nC
Reverse Recovery Time	T_{rr}	$I_F = 20A, di/dt = 100A/\mu s$		18		ns
Source-Drain Diode characteristics						
Diode Forward voltage ⁽³⁾	V_{DS}	$V_{GS} = 0V, I_S = 10A$	-	-	1.2	V
Diode Forward current ⁽⁴⁾	I_S		-	-	40	A

Notes:

1. Repetitive Rating: pulse width limited by maximum junction temperature
2. EAS Condition: $T_J = 25^{\circ}\text{C}, V_{DD} = 30V, R_G = 25\Omega, L = 0.5\text{Mh}$
3. Pulse Test: pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$
4. Surface Mounted on FR4 Board, $t \leq 10\text{ sec}$

Test Circuit

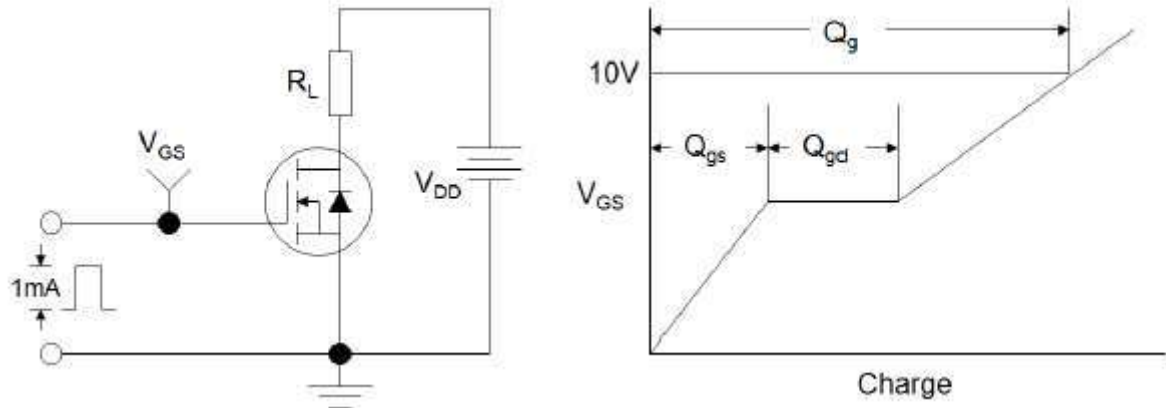


Figure 1: Gate Charge Test Circuit & Waveform

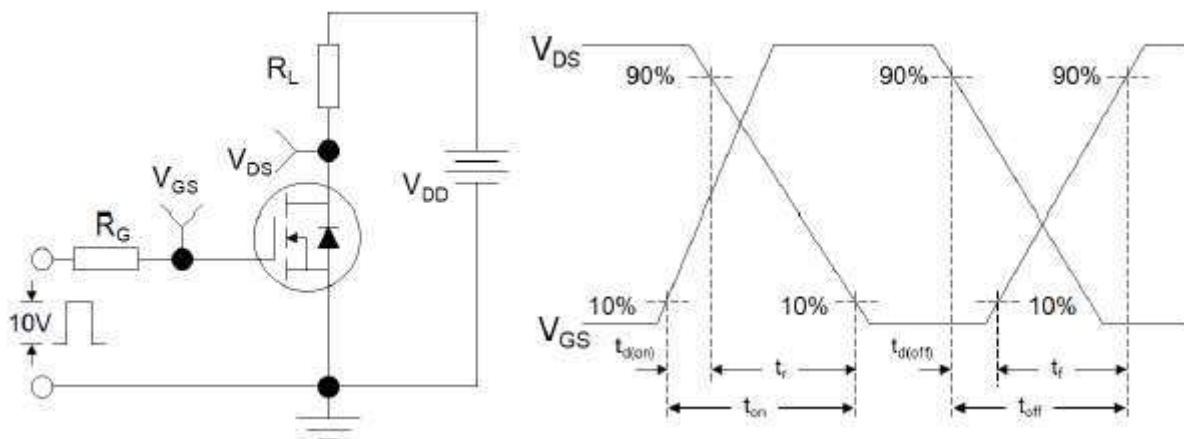


Figure 2: Resistive Switching Test Circuit & Waveforms

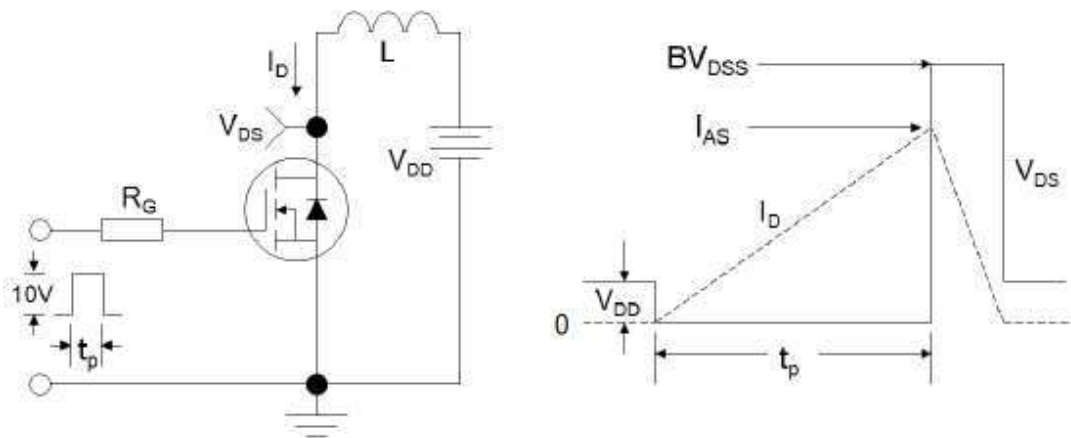


Figure 3: Unclamped Inductive Switching Test Circuit & Waveforms

RATING AND CHARACTERISTICS CURVES (RMD40N60DFV)

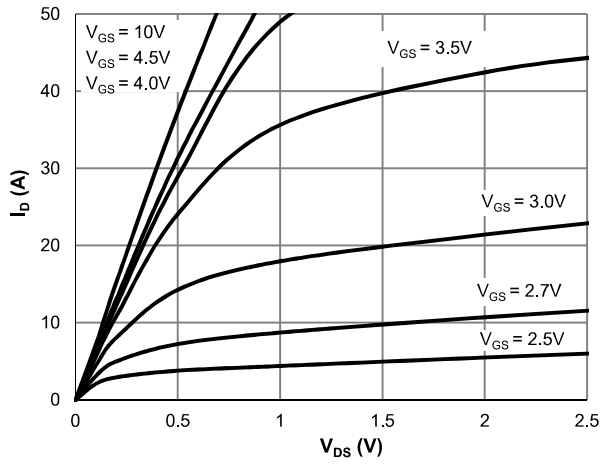


Figure 1: Saturation Characteristics

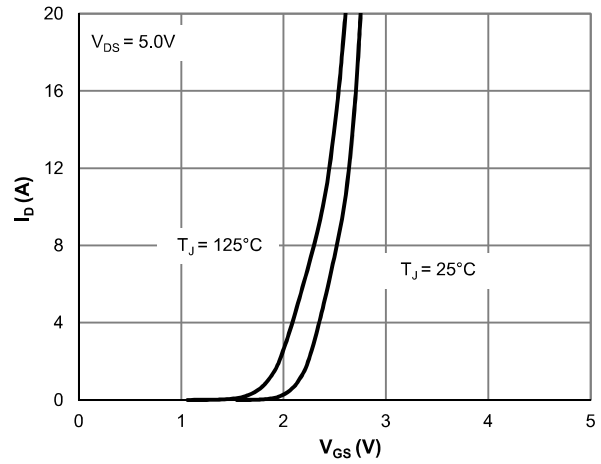


Figure 2: Transfer Characteristics

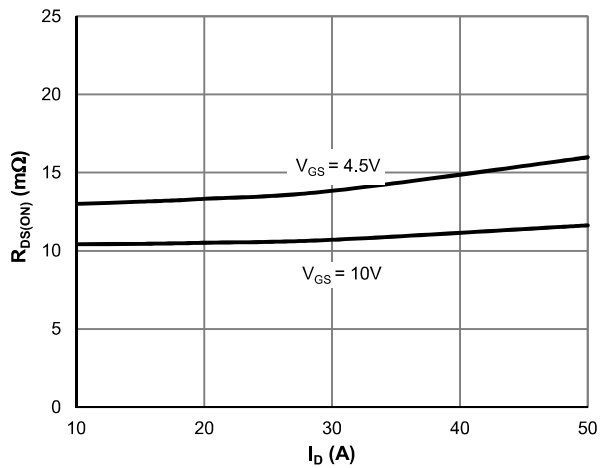


Figure 3: $R_{DS(ON)}$ vs. Drain Current

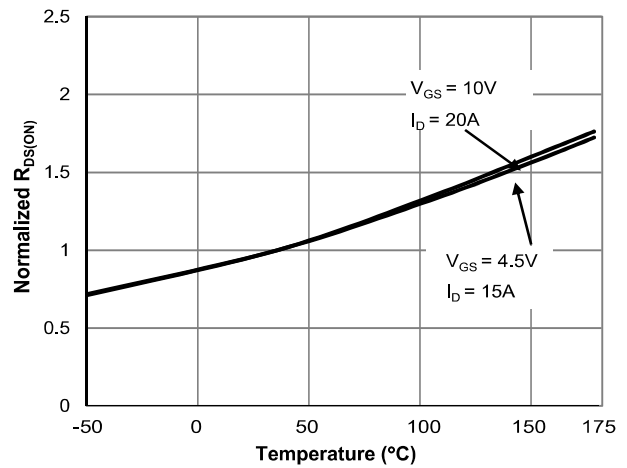


Figure 4: $R_{DS(ON)}$ vs. Junction Temperature

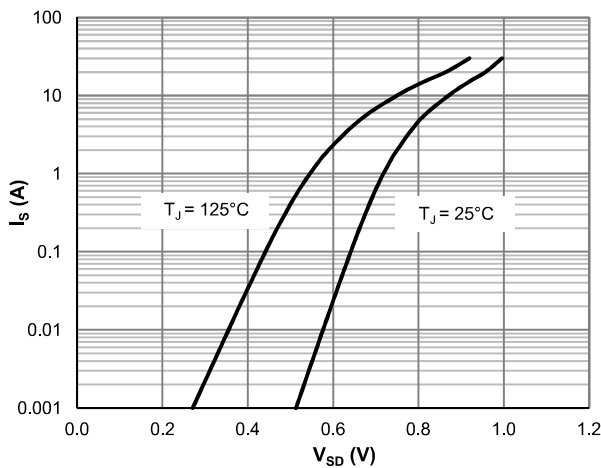


Figure 5: Body-Diode Characteristics

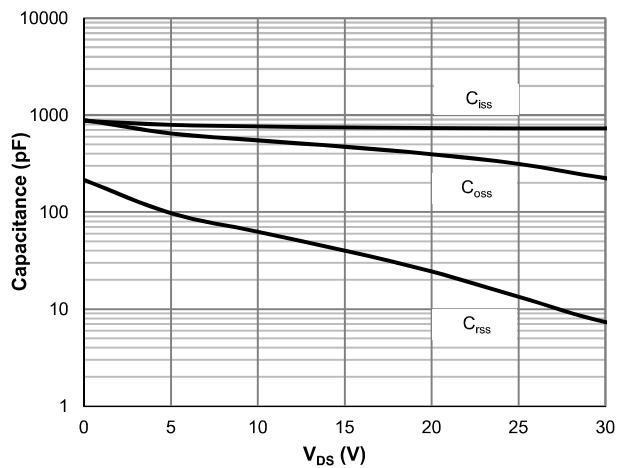


Figure 6: Capacitance Characteristics

RATING AND CHARACTERISTICS CURVES (RMD40N60DFV)

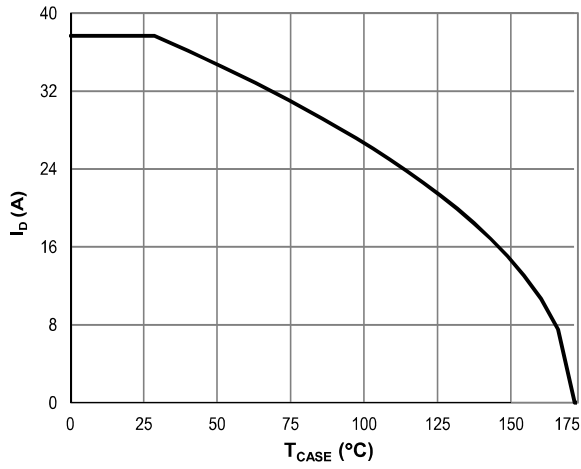


Figure 7: Current De-rating

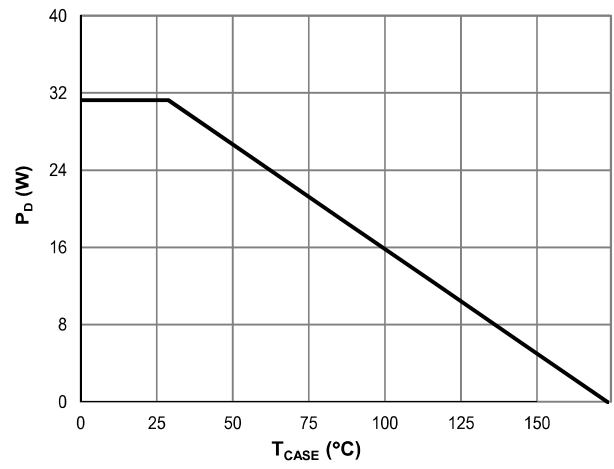


Figure 8: Power De-rating

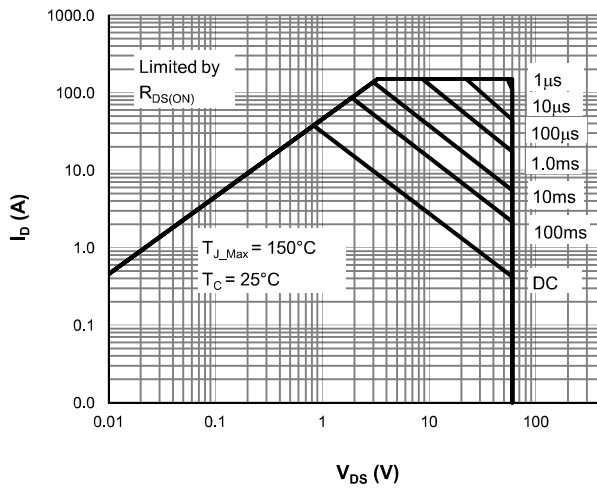


Figure 9: Maximum Safe Operating Area

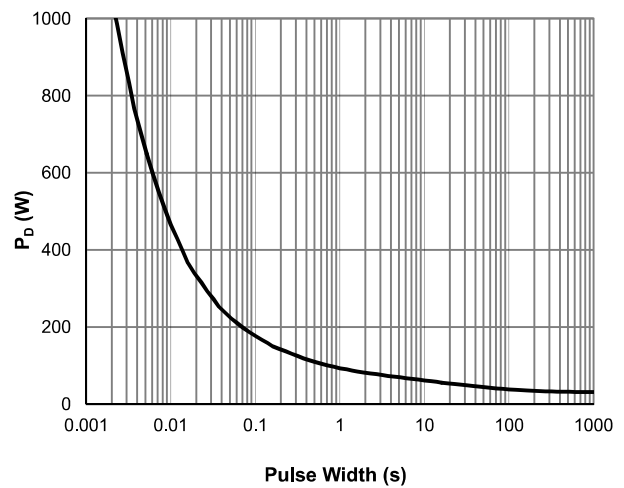


Figure 10: Single Pulse Power Rating, Junction-to-Case

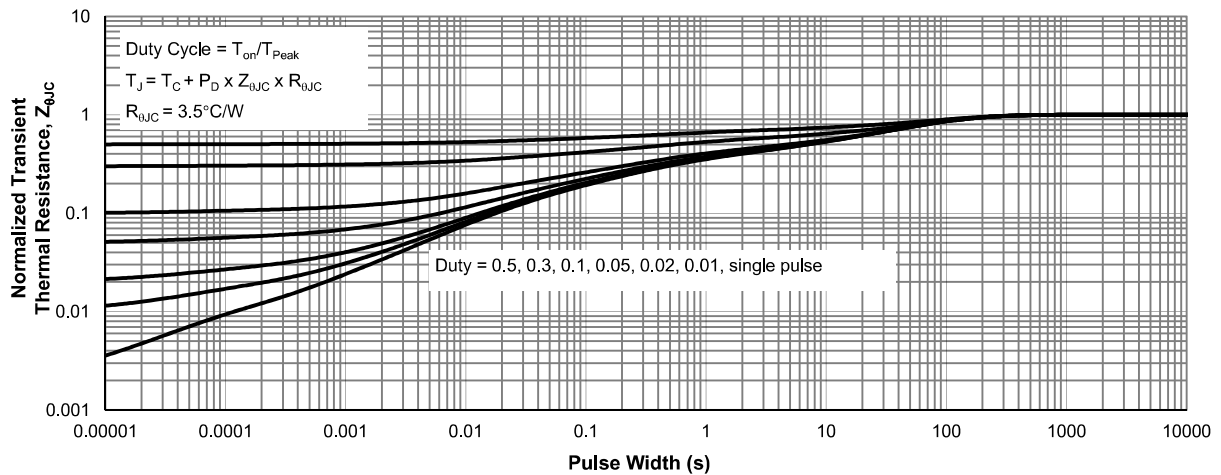
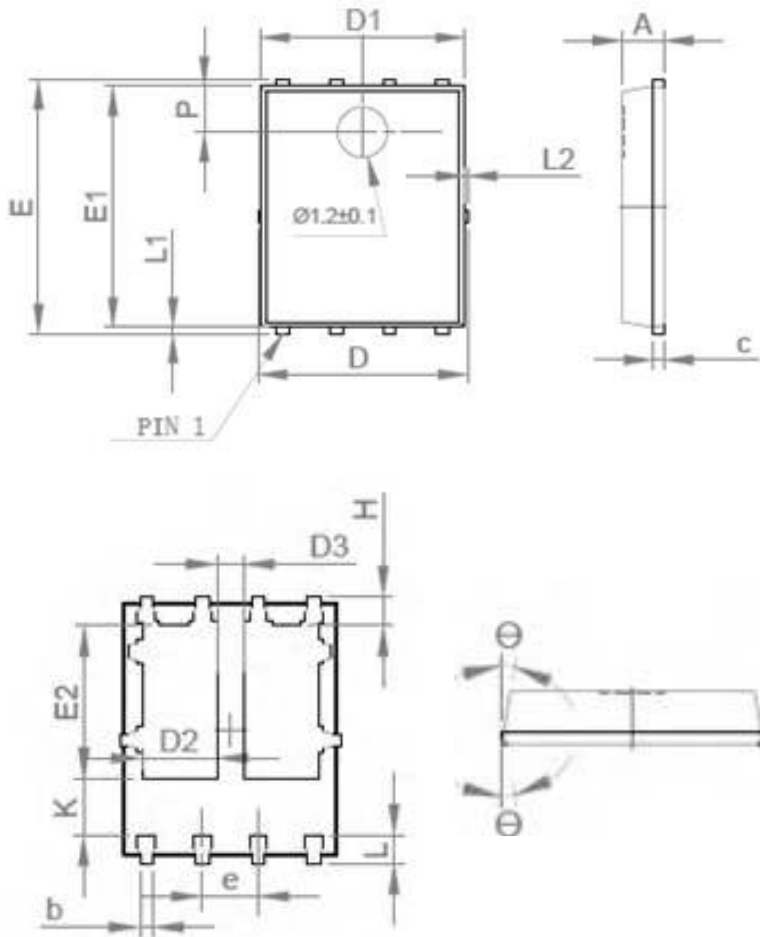


Figure 11: Normalized Maximum Transient Thermal Impedance

Package Mechanical Data



SYMBOL	MIN	NOM	MAX
A	0.90	1.00	1.10
b	0.25	0.30	0.35
c	0.21	0.25	0.34
D	-	-	5.10
D1	4.80	4.90	5.00
D2	1.605	1.705	1.805
D3	0.55	0.60	0.65
e	1.27 BSC		
E	5.90	6.00	6.10
E1	5.70	5.75	5.80
E2	3.375	3.475	4.475
H	0.55	0.65	0.75
K	1.20	-	-
L	0.60	0.65	0.70
L1	0.05	0.15	0.25
L2	-	-	0.12
θ	8°	10°	12°
P	1.00	1.10	1.20



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